

LOCTITE 322

February 2018

PRODUCT DESCRIPTION

LOCTITE 322 provides the following product characteristics:

Technology	Acrylic
Chemical Type	Acrylate
Appearance (uncured)	Transparent pale yellow colored liquid ^{LMS}
Components	One component - requires no mixing
Viscosity	Medium
Cure	Ultraviolet (UV) light
Cure Benefit	Production - high speed curing
Application	Bonding

LOCTITE 322 bonds and seals clear plastic to metal.

ISO-10993

An ISO 10993 Test Protocol is an integral part of the Quality Program for LOCTITE 322. LOCTITE 322 has been qualified to Henkel's ISO 10993 Protocol as a means to assist in the selection of products for use in the medical device industry. Certificates of Compliance are available on Henkel's website or through the Henkel Quality Department.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Specific Gravity @ 25°C 1.0
Flash Point - See SDS

Viscosity, Brookfield - RVT, 25 °C, mPa·s (cP):
Spindle 5, speed 20 rpm 4,200 to 7,000^{LMS}

TYPICAL CURING PERFORMANCE

LOCTITE 322 is cured when exposed to UV radiation at 365nm. To obtain a full cure on surfaces exposed to air, radiation at 250nm is also required. The speed of cure will depend on the UV intensity as measured at the product surface. Typical cure condition is 5-10 seconds at 100mW/cm² using a medium pressure, quartz envelope, mercury vapor lamp.

Tack Free Time

Tack Free Time is the time required to achieve a tack free surface

Tack Free Time, seconds:
100 mW/cm², measured @ 365 nm 3 to 7

Fixture Time

Fixture time is defined as the time to develop a shear strength of 0.1 N/mm².

UV Fixture Time, Glass microscope slides, seconds:

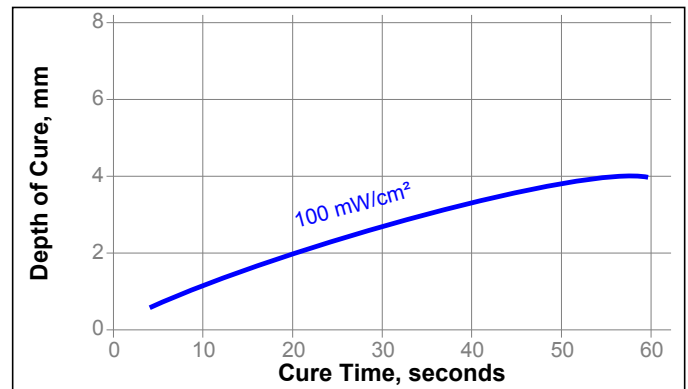
Black light, Zeta[®] 7500 light source:
6 mW/cm², measured @ 365 nm ≤12^{LMS}

UV Fixture Time, Glass, seconds:

100 mW/cm², measured @ 365 nm 1 to 5

Depth of Cure

The graph below shows the increase in depth of cure with time at 100mW/cm² as measured from the thickness of the cured pellet formed in a 15mm diameter PTFE die.



TYPICAL PROPERTIES OF CURED MATERIAL

Physical Properties

Coefficient of Thermal Expansion, ISO 11359-2, K ⁻¹	80×10 ⁻⁶
Coefficient of Thermal Conductivity, ISO 8302, W/(m·K)	0.1
Glass Transition Temperature, ASTM E 228, °C	45
Shore Hardness, ISO 868, Durometer D	68
Shrinkage, %	8
Elongation, at break, ISO 527-3, %	160
Tensile Strength, at break, ISO 527-3	N/mm ² 9 (psi) (1,305)
Tensile Modulus, ISO 527-3	N/mm ² 420 (psi) (61,000)

UV Depth of Cure, mm:
 100 mW/cm², measured @ 365 nm, for 30 >0.9^{MS} seconds

TYPICAL PERFORMANCE OF CURED MATERIAL

Cured @ 100 mW/cm² @365 nm for 40 seconds.

Adhesive Properties

Lap Shear Strength, ISO 4587:	
PVC to Glass	N/mm ² 1 to 5 (psi) (145 to 725)
Polycarbonate to Glass	N/mm ² 1 to 5 (psi) (145 to 725)
ABS to Glass	N/mm ² 1 to 5 (psi) (145 to 725)
Tensile Strength, ISO 6922:	
Steel pin (grit blasted)Glass	N/mm ² 4 to 11 (psi) (580 to 1,600)

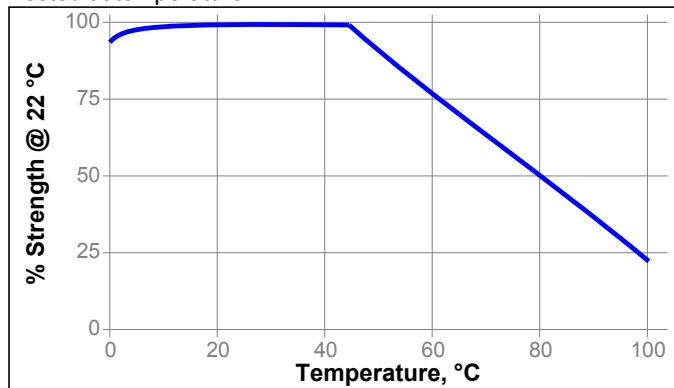
TYPICAL ENVIRONMENTAL RESISTANCE

Cured @ 100 mW/cm², measured @ 365 nm, for 40 seconds plus 1 week @ 22 °C

Tensile Strength, ISO 6922:
 Steel pin (grit blasted) to Glass

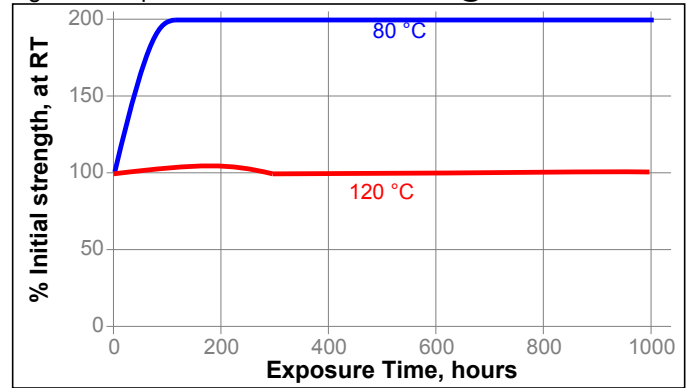
Hot Strength

Tested at temperature



Heat Aging

Aged at temperature indicated and tested @ 22 °C



Chemical/Solvent Resistance

Aged under conditions indicated and tested @ 22 °C.

Environment	°C	% of initial strength		
		100 h	500 h	1000 h
Heat/humidity 90% RH	40	65	40	30
Gasoline	22	85	85	85
Freon TA	22	85	75	0
Industrial methylated spirits	22	80	10	0

Effects of Sterilization

Components bonded with LOCTITE 322 and subjected to standard sterilization by ETO or Gamma Radiation (2.5 and 7.0 Megarads) resulted in no deterioration of bond strength

GENERAL INFORMATION

This product is not recommended for use in pure oxygen and/or oxygen rich systems and should not be selected as a sealant for chlorine or other strong oxidizing materials.

For safe handling information on this product, consult the Safety Data Sheet (SDS).

Where aqueous washing systems are used to clean the surfaces before bonding, it is important to check for compatibility of the washing solution with the adhesive. In some cases these aqueous washes can affect the cure and performance of the adhesive.

Directions for use:

1. This product is light sensitive; exposure to daylight, UV light and artificial lighting should be kept to a minimum during storage and handling.
2. The product should be dispensed from applicators with black feedlines.
3. For best performance bond surfaces should be clean and free from grease.
4. Cure rate is dependent on lamp intensity, distance from light source, depth of cure needed or bondline gap and light transmittance of the substrate through which the radiation must pass.
5. Recommended intensity for cure in bondline situation is 5 mW/cm² minimum (measured at the bondline) with an exposure time of 4-5 times the fixture time at the same intensity.
6. For dry curing of exposed surfaces, higher intensity UV is required (100 mW/cm²).
7. Cooling should be provided for temperature sensitive substrates such as thermoplastics.
8. Plastic grades should be checked for risk of stress cracking when exposed to liquid adhesive.
9. Excess adhesive can be wiped away with organic solvent.
10. Bonds should be allowed to cool before subjecting to any service loads.

Loctite Material Specification^{LMS}

LMS dated July 31, 1996. Test reports for each batch are available for the indicated properties. LMS test reports include selected QC test parameters considered appropriate to specifications for customer use. Additionally, comprehensive controls are in place to assure product quality and consistency. Special customer specification requirements may be coordinated through Henkel Quality.

Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: 8 °C to 21 °C. Storage below 8 °C or greater than 28 °C can adversely affect product properties.

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Conversions

(°C x 1.8) + 32 = °F
 kV/mm x 25.4 = V/mil
 mm / 25.4 = inches
 µm / 25.4 = mil
 N x 0.225 = lb
 N/mm x 5.71 = lb/in
 N/mm² x 145 = psi
 MPa x 145 = psi
 N·m x 8.851 = lb·in
 N·m x 0.738 = lb·ft
 N·mm x 0.142 = oz·in
 mPa·s = cP

Note

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